



80A 2601-CIP.

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

#12
5/11/99
Pgen

In re Application of:

KENICHI NAKAMURA)

Serial No. 08/884,778)

Filed: June 30, 1997)

For: BIODEGRADABLE MOLDING)
MATERIAL)

Group Art Unit: 1755

Examiner: M. Marcheschi

LETTER

Hon. Commissioner of Patents and Trademarks
Washington, D.C. 20231

Dear Sir:

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MAR 11 1999
GROUP 1700

In connection with the above-identified application, enclosed herewith please find two
(2) certified copies of the corresponding Japanese Patent Applications No. 8-78400 filed on March
5, 1996 and No. 9-152828 filed on May 26, 1997, upon which Convention Priority is claimed.

Respectfully submitted,

KODA AND ANDROLIA

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